

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS300N08S5N011	**Issued**	23. June 2021
MA#	MA005430875		
Package	PG-HSOG-8-1	**Weight***	708.76 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.727	1.09	1.09	10903	10903
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		190	
	non noble metal	copper	7440-50-8	134.219	18.94	18.97	189372	189619
wire	non noble metal	aluminium	7429-90-5	19.435	2.74	2.74	27422	27422
encapsulation	inorganic material	zincoxide	1314-13-2	2.564	0.36		3617	
	miscellaneous	miscellaneous	-	10.254	1.45		14468	
	plastics	epoxy resin	-	38.453	5.43		54254	
	inorganic material	silicondioxide	60676-86-0	205.083	28.94	36.18	289356	361695
leadfinish	non noble metal	tin	7440-31-5	8.309	1.17	1.17	11723	11723
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	310	311
solder	non noble metal	tin	7440-31-5	0.125	0.02		176	
	noble metal	silver	7440-22-4	0.156	0.02		221	
	non noble metal	lead	7439-92-1	5.973	0.84	0.88	8427	8824
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		117	
	non noble metal	iron	7439-89-6	0.276	0.04		389	
	non noble metal	copper	7440-50-8	275.705	38.89	38.94	388997	389503
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com